

PCN#20160607002 Qualification of new Assembly & Test site (TI Taiwan) & New material set for the UCCx895DW Device family Change Notification / Sample Request

Date: 6/10/2016 To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN_ww_admin_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

20160607002 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

CUSTOMER PART NUMBER

UCC3895DW UCC3895DWTR null null

Technical details of this Product Change follow on the next page(s).

| PCN Number: | | | 20160607002 PCN Date: 6/10/201 | | | | | | 6/10/2016 | | | | |
|--|------------|---------|---|---------------|---|---------------------------|-------------------------|--------------|--------------------|----------------------------------|------------|--------|-----------------|
| Title: Qualification of new Assembly & Test site (TI Taiwan) & New material set for the UCCx895DW Device family | | | | | | for the | | | | | | | |
| Custom | | PCN / | | | Dept | : | Quality Se | rvice | es | | | | |
| Proposed 1 st Ship Da | | | :e: | 9/ | /10/2016 | Est | Estimated Sample Availa | | ability: | bility: Provided upon Request | | | |
| Change | | | | | | | | | | | | | |
| | embly Site | 3 | Assembly Pi | | | ocess | | \boxtimes | Assembly Materials | | | | |
| Desi | | | | Electrical Sp | | | | | | Mechanical Specification | | | ification |
| | Site | <u></u> | ┥┝ | ╡┼ | Packing/Sh | | | | Test Process | | | | |
| | er Bump S | | | Wafer Bump | | | | | | | er Bum | | |
| | er Fab Sit | e | | ╡┼ | Wafer Fab | | | | | wai | fer Fab F | roce | SS |
| | | | | | Part numb | | | | L | | | | |
| Descript | tion of C | | | | | PUN | De | tails | | | | | |
| | tion of Cl | | | d +/ | | the c | | ification TI | Taire | van a | c an ada | lition | al Assembly & |
| | | | | | | | | M differen | | | | | al Assellibly & |
| | V | Vhat | | | | | Ca | rsem | | TI 1 | 「aiwan | | |
| | Ν | 1ount | Corr | про | und | S | ID# | 434165 | | 414 | 47858 | | |
| Mold | | 1old C | d Compound | | | S | ID# | 438359 | 438359 421 | | | | |
| Bond | | Bond V | nd Wire | | | A | ۹u, | 1.3 mils | (| Cu, 0.96 mils | | | |
| | L | .eadfra | dframe | | | | Sta | andard | | Roughened | | | |
| Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ. Reason for Change: Continuity of Supply | | | | | | | | | | | | | |
| | <u> </u> | · | h Fit | . Fo | orm. Func | tion. (| Oua | ality or Re | liab | ility (| nositiv | e / 1 | negative): |
| None | | | | | , | | 2 | | | | | - / - | |
| Anticipa | ited impa | act or | n Ma | iter | ial Declar | ation | | | | | | | |
| Material Declaration | | | Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI ECO website</u> . | | | | | | | | | | |
| Changes | s to prod | uct ic | lent | ific | ation resu | ulting | fro | om this PC | N: | | | | |
| Assen | nbly Site | Ass | Assembly Site Origin (22L) | | 2L) As | Assembly Country Code (21 | | e (21L | .) Assembly C | | embly City | | |
| Ca | rsem | | CAR | | | MYS | | Ipoh | | Ipoh | | | |
| ТІТ | aiwan | | TAI | | | TWN | | Chun | ig Ho | o, New Taipei City | | | |
| Sample p | product sh | nipping | g lab | bel | (not actua | al prod | luct | label) | | | • | | |

| MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 (31T)LOT: 3959047/ML MSL 1 /235C/UNLIM 03/29/04 MSL 2 /260C/1 YEAR SEAL DT (4W) TKY (1T) 7523483 OPT: 39 (1)TO:1750 (2P) REV: (V) 0033 ITEM: 39 (2D) CSO: SHE (21L) CCO: | 523483SI2) 0033317 1L) CC0:USA | |
|--|---------------------------------------|--|
|--|---------------------------------------|--|

Topside Device marking (if included): Assembly site code for CAR= V Assembly site code for TAI = T

Product Affected

| | | | | _ |
|-------------|---------------|-------------|---------------|---|
| UCC2895DW | UCC2895DWTR | UCC3895DW | UCC3895DWTR | |
| UCC2895DWG4 | UCC2895DWTRG4 | UCC3895DWG4 | UCC3895DWTRG4 | |



TI Information Selective Disclosure

Qualification Report UCC3895DWTR Assembly and Test Offload to TITL with Copper Wire

Product Attributes

| Attributes | Qual Device: UCC3895DWTR | QBS Package Reference: ADS820U_QMI505MT_CU _SSTN | QBS Package Reference: ADS8504IBDW_QMI505 MT_CU_STD | QBS Package Reference: TPS2101D | QBS Package Reference: TSS721AD | QBS Package Reference: ULQ2003AQDRQ1_STDLF |
|------------------------|-----------------------------|--|--|------------------------------------|---------------------------------------|---|
| Assembly Site | TAI | TAI | TAI | TAI | TAI | FMX |
| Package Family | SOIC WIDE | SOIC | SOIC | SOIC | SOIC | SOIC |
| Flammability Rating | - | UL 94 V-0 | UL 94 V-0 | UL 94 V-0 | UL 94 V-0 | UL 94 V-0 |
| Wafer Fab Supplier | SFAB | TSMC WF2 | DMOS5 | DFAB | SFAB | SFAB |
| Wafer Fab Process | IMP-PWR2 | 0.60UM-TSMC | 50HPA07 | LBC3S | JI1 | JI1-SLM |

- QBS: Qual By Similarity

- Qual Device UCC3895DWTR is qualified at LEVEL2-260C

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition | Duration | Qual Device: UCC3895DWTR | QBS Package Reference: ADS820U_QMI505MT _CU_SSTN | QBS Package Reference: ADS8504IBDW_QMI505 MT_CU_STD | QBS Package Reference: TPS2101D | QBS Package Reference: TSS721AD | QBS Package Reference: ULQ2003AQDRQ1_ST DLF |
|--|---|---|--|---|--|---------------------------------------|---------------------------------------|--|
| AC | Autoclave 121C | 96 Hours | - | - | 1/77/0 | - | - | 3/231/0 |
| HAST | Biased HAST, 130C/85%R H | 96 Hours | - | - | - | - | - | 3/231/0 |
| HTOL | Life Test, 150C | 408 Hours | - | - | - | - | - | 3/231/0 |
| HTSL | High Temp Storage Bake 150C | 1000 Hours | - | - | - | - | - | 1/45/0 |
| HTSL | High Temp Storage Bake 170C | 420 Hours | - | - | 1/77/0 | - | - | - |
| тс | Temperature Cycle, - 65/150C | 500 Cycles | - | 3/231/0 | 1/77/0 | 3/231/0 | 3/231/0 | 3/231/0 |
| WBP | Bond Pull | Wires | Pass | - | - | - | - | - |
| WBS | Ball Bond Shear | Wires | Pass | - | - | - | - | - |
| - The foll - The foll - The foll Quality as Green/Pt | owing are equival owing are equival owing are equival | ent HTOL options ent HTSL options ent Temp Cycle o data is available | based on an activation based on an activation | energy of 0.7eV : 125C/1k H energy of 0.7eV : 150C/1k H C/125C/700 Cycles and -65 | re Cycle, Thermal Shock, and lours, 140C/480 Hours, 150C/ lours, and 170C/420 Hours C/150C/500 Cycles | | Hours | |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--------------------------------|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |